



SOT566-3

plastic, heatsink small outline package; 24 leads; low stand-off height

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	HSOP24
Package type industry code	HSOP24
Package style descriptive code	HSOP (heatsink small outline package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	23-7-2003

Table 1. Package summary

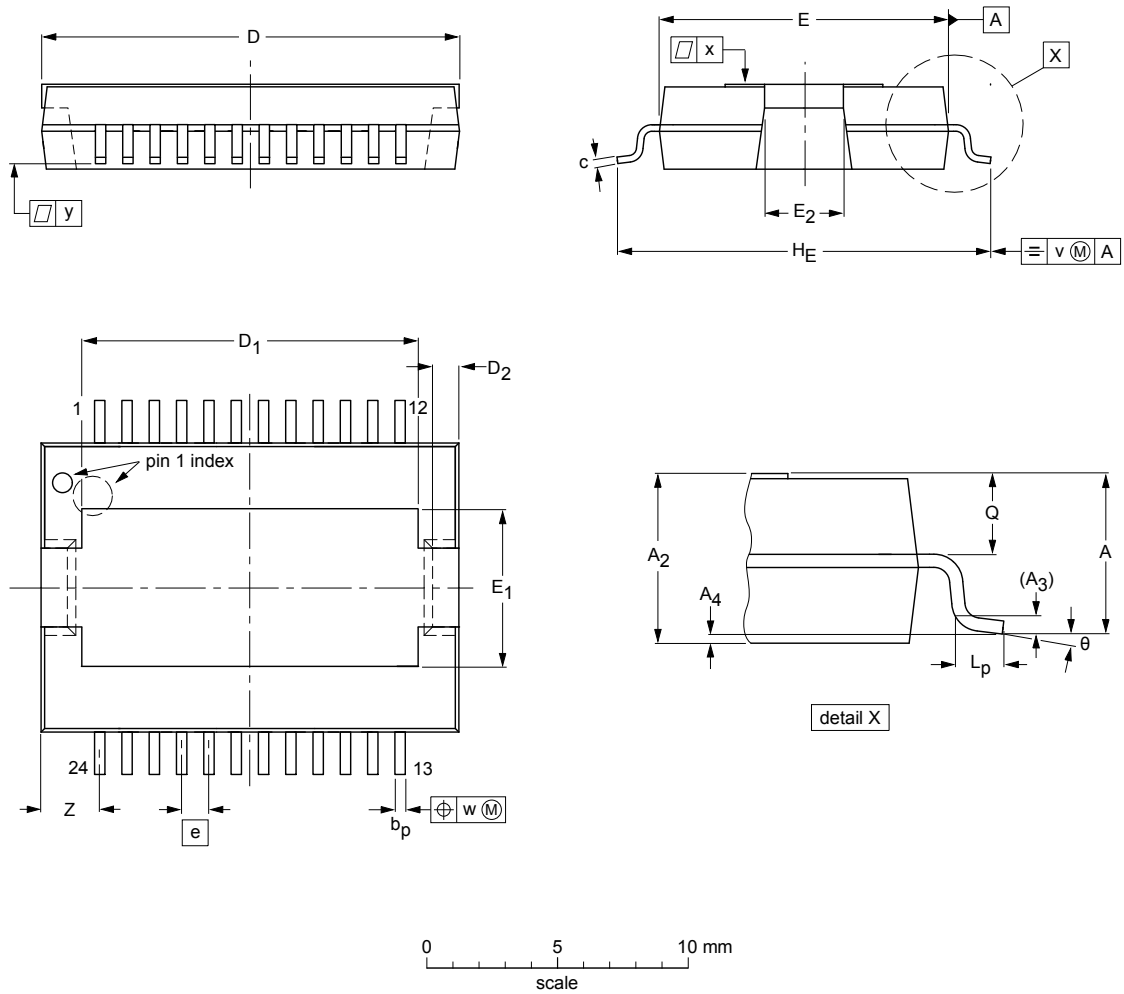
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	15.8	-	15.9	16	mm
E	package width	10.9	-	11	11.1	mm
A	seated height	[tbd]	-	3.5	3.5	mm
A ₂	package height	3.2	-	3.35	3.5	mm
n ₂	actual quantity of termination	-	-	24	-	



2. Package outline

HSOP24: plastic, heatsink small outline package; 24 leads; low stand-off height

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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₂	A ₃	A ₄ ⁽¹⁾	b _p	c	D ⁽²⁾	D ₁	D ₂	E ⁽²⁾	E ₁	E ₂	e	H _E	L _p	Q	v	w	x	y	Z	θ
mm	3.5	3.5 3.2	0.35	+0.08 -0.04	0.53 0.40	0.32 0.23	16.0 15.8	13.0 12.6	1.1 0.9	11.1 10.9	6.2 5.8	2.9 2.5	1	14.5 13.9	1.1 0.8	1.7 1.5	0.25	0.25	0.03	0.07	2.7 2.2	8° 0°

Notes

- Limits per individual lead.
- Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT566-3						-03-02-18 03-07-23

Fig. 1. Package outline HSOP24 (SOT566-3)

3. Legal information

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4. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Legal information.....	3

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